

## NCE N-Channel Enhancement Mode Power MOSFET

### Description

The NCE6080 uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications.

### General Features

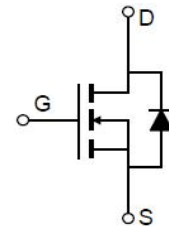
- $V_{DS} = 60V, I_D = 80A$   
 $R_{DS(ON)} < 8.5m\Omega @ V_{GS} = 10V$
- High density cell design for ultra low  $R_{DS(ON)}$
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high  $E_{AS}$
- Excellent package for good heat dissipation

### Application

- PWM
- Load Switching

**100% UIS TESTED!**

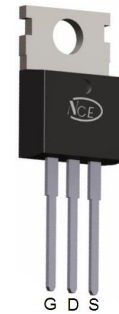
**100%  $\Delta V_{ds}$  TESTED!**



Schematic diagram



Marking and pin assignment



TO-220-3L top view

### Package Marking and Ordering Information

| Device Marking | Device  | Device Package | Reel Size | Tape width | Quantity |
|----------------|---------|----------------|-----------|------------|----------|
| NCE6080        | NCE6080 | TO-220-3L      | -         | -          | -        |

### Absolute Maximum Ratings ( $T_c = 25^\circ C$ unless otherwise noted)

| Parameter  | Symbol             | Limit      | Unit          |
|--|--------------------|------------|---------------|
| Drain-Source Voltage                             | $V_{DS}$           | 60         | V             |
| Gate-Source Voltage                              | $V_{GS}$           | $\pm 20$   | V             |
| Drain Current-Continuous                         | $I_D$              | 80         | A             |
| Drain Current-Continuous( $T_c = 100^\circ C$ )  | $I_D(100^\circ C)$ | 56.5       | A             |
| Pulsed Drain Current                             | $I_{DM}$           | 320        | A             |
| Maximum Power Dissipation                        | $P_D$              | 110        | W             |
| Derating factor                                  |                    | 0.73       | W/ $^\circ C$ |
| Single pulse avalanche energy (Note 5)           | $E_{AS}$           | 390        | mJ            |
| Operating Junction and Storage Temperature Range | $T_J, T_{STG}$     | -55 To 175 | $^\circ C$    |

## Thermal Characteristic

|  |                 |      |                      |
|--|-----------------|------|----------------------|
| Thermal Resistance, Junction-to-Case <sup>(Note 2)</sup> | $R_{\theta JC}$ | 1.36 | $^{\circ}\text{C/W}$ |
|--|-----------------|------|----------------------|

## Electrical Characteristics ( $T_c=25^{\circ}\text{C}$ unless otherwise noted)

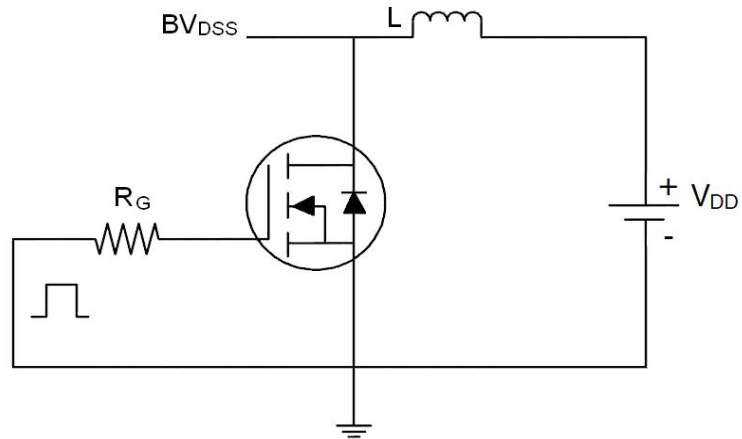
| Parameter                          | Symbol              | Condition  | Min | Typ  | Max  | Unit |
|------------------------------------|---------------------|--|-----|------|------|------|
| Off Characteristics                |                     |  |     |      |      |      |
| Drain-Source Breakdown Voltage     | BV <sub>DSS</sub>   | V <sub>GS</sub> =0V I <sub>D</sub> =250μA  | 60  | -    | -    | V    |
| Zero Gate Voltage Drain Current    | I <sub>DSS</sub>    | V <sub>DS</sub> =60V, V <sub>GS</sub> =0V  | -   | -    | 1    | μA   |
| Gate-Body Leakage Current          | I <sub>GSS</sub>    | V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V   | -   | -    | ±100 | nA   |
| On Characteristics (Note 3)        |                     |  |     |      |      |      |
| Gate Threshold Voltage             | V <sub>GS(th)</sub> | V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA                             | 2   | 2.8  | 4    | V    |
| Drain-Source On-State Resistance   | R <sub>DS(ON)</sub> | V <sub>GS</sub> =10V, I <sub>D</sub> =20A  | -   | 6    | 8.5  | mΩ   |
| Forward Transconductance           | g <sub>FS</sub>     | V <sub>DS</sub> =5V, I <sub>D</sub> =20A   | 20  | -    | -    | S    |
| Dynamic Characteristics (Note4)    |                     |  |     |      |      |      |
| Input Capacitance                  | C <sub>iss</sub>    | V <sub>DS</sub> =30V, V <sub>GS</sub> =0V,<br>F=1.0MHz                               | -   | 4000 | -    | pF   |
| Output Capacitance                 | C <sub>oss</sub>    |  | -   | 290  | -    | pF   |
| Reverse Transfer Capacitance       | C <sub>rss</sub>    |  | -   | 210  | -    | pF   |
| Switching Characteristics (Note 4) |                     |  |     |      |      |      |
| Turn-on Delay Time                 | t <sub>d(on)</sub>  | V <sub>DD</sub> =30V, R <sub>L</sub> =1Ω<br>V <sub>GS</sub> =10V, R <sub>G</sub> =3Ω | -   | 8.5  | -    | nS   |
| Turn-on Rise Time                  | t <sub>r</sub>      |  | -   | 7    | -    | nS   |
| Turn-Off Delay Time                | t <sub>d(off)</sub> |  | -   | 40   | -    | nS   |
| Turn-Off Fall Time                 | t <sub>f</sub>      |  | -   | 15   | -    | nS   |
| Total Gate Charge                  | Q <sub>g</sub>      | V <sub>DS</sub> =30V, I <sub>D</sub> =20A,<br>V <sub>GS</sub> =10V                   | -   | 90   | -    | nC   |
| Gate-Source Charge                 | Q <sub>gs</sub>     |  | -   | 9    | -    | nC   |
| Gate-Drain Charge                  | Q <sub>gd</sub>     |  | -   | 18   | -    | nC   |
| Drain-Source Diode Characteristics |                     |  |     |      |      |      |
| Diode Forward Voltage (Note 3)     | V <sub>SD</sub>     | V <sub>GS</sub> =0V, I <sub>S</sub> =20A   | -   | -    | 1.2  | V    |
| Diode Forward Current (Note 2)     | I <sub>S</sub>      |  | -   | -    | 80   | A    |
| Reverse Recovery Time              | t <sub>rr</sub>     | T <sub>J</sub> = 25°C, I <sub>F</sub> = 20A<br>di/dt = 100A/μs (Note3)               | -   | 32   | -    | nS   |
| Reverse Recovery Charge            | Q <sub>rr</sub>     |  | -   | 45   | -    | nC   |
| Forward Turn-On Time               | t <sub>on</sub>     | Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)                 |     |      |      |      |

### Notes:

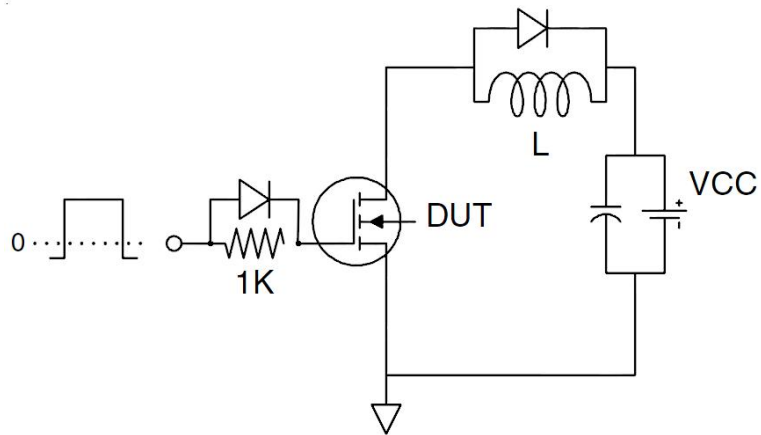
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production
5.  $E_{AS}$  condition :  $T_J=25^{\circ}\text{C}, V_{DD}=20V, V_G=10V, L=0.5\text{mH}, R_g=25\Omega$

## Test circuit

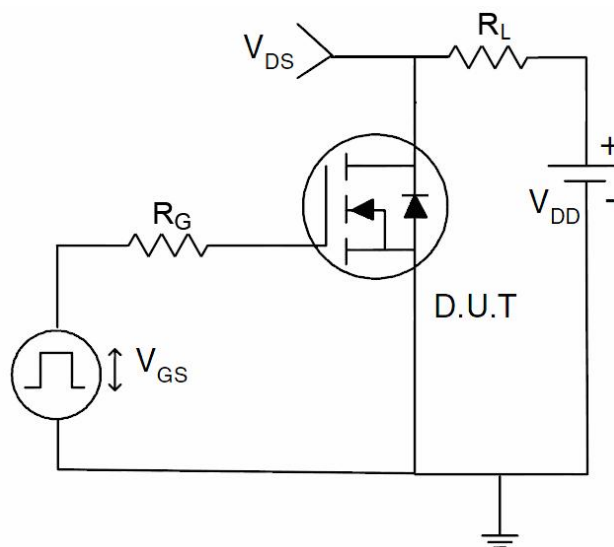
### 1) $E_{AS}$ Test Circuit



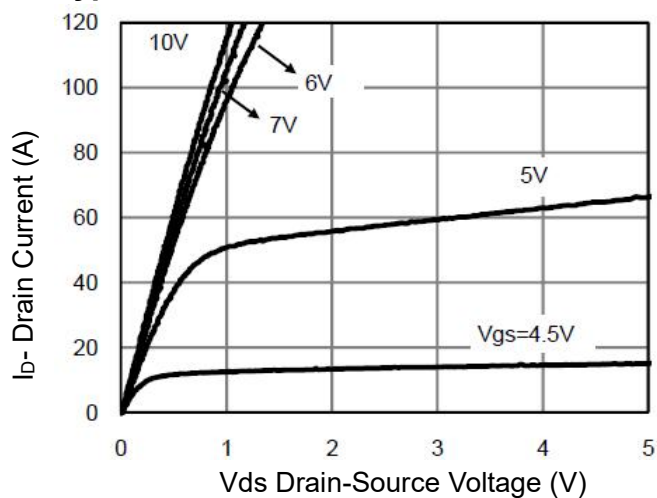
### 2) Gate Charge Test Circuit



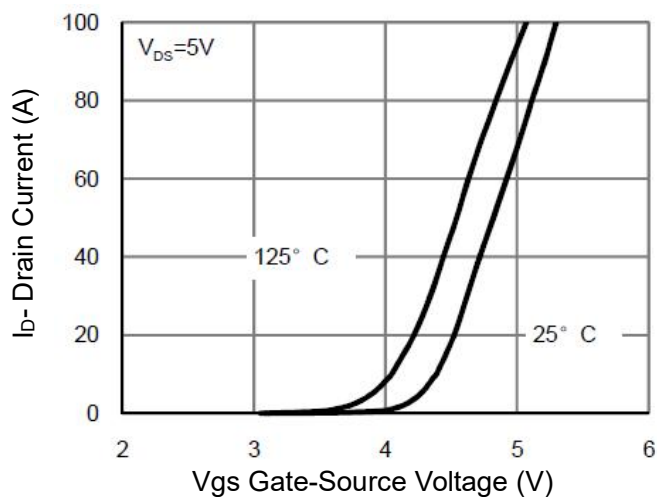
### 3) Switch Time Test Circuit



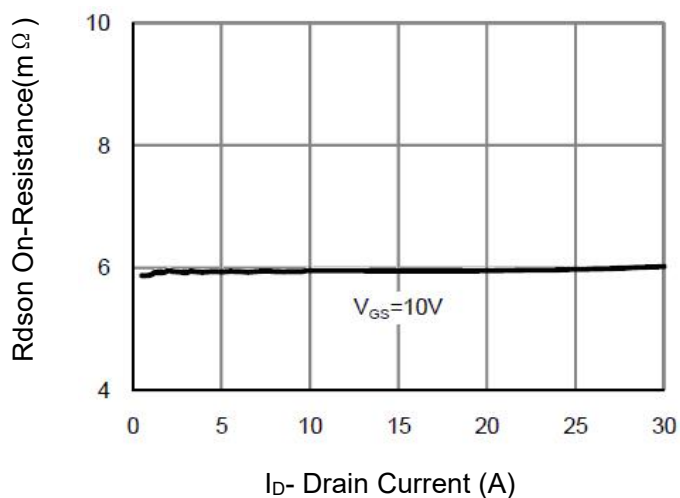
## Typical Electrical and Thermal Characteristics (Curves)



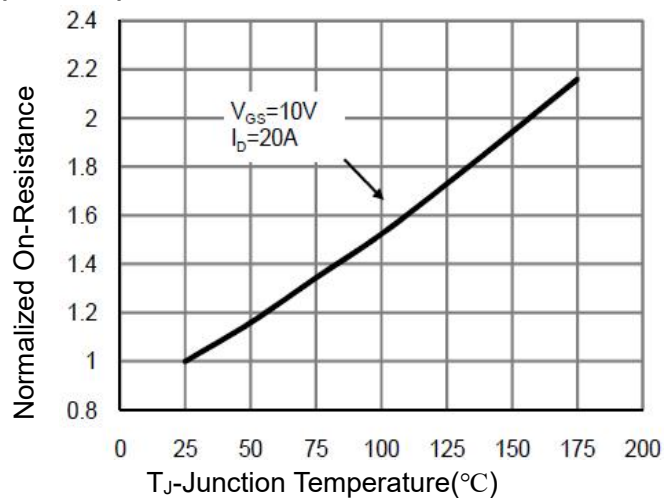
**Figure 1 Output Characteristics**



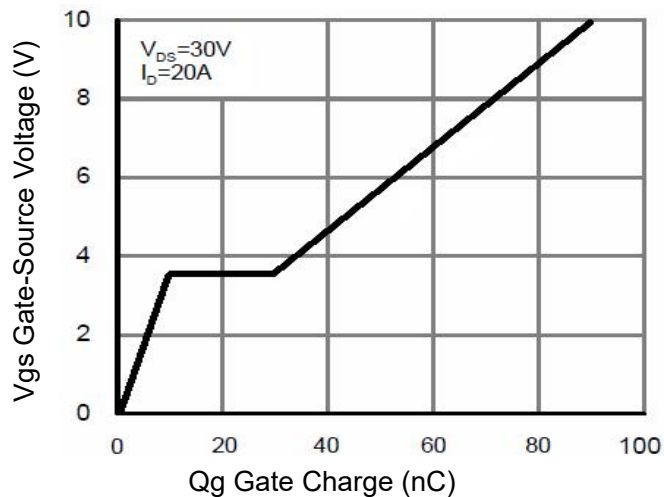
**Figure 2 Transfer Characteristics**



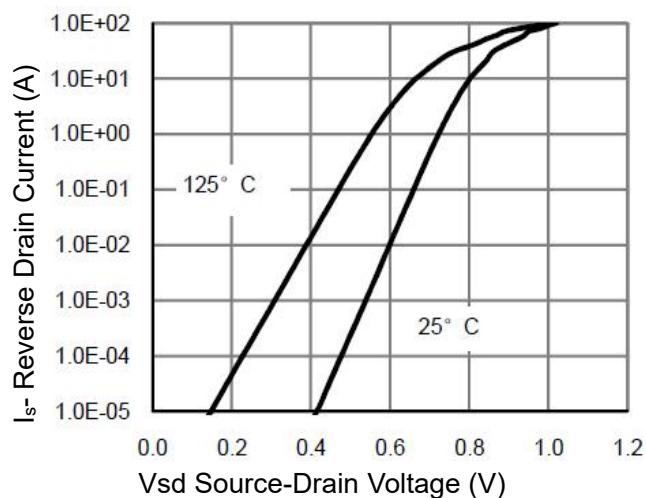
**Figure 3 Rdson- Drain Current**



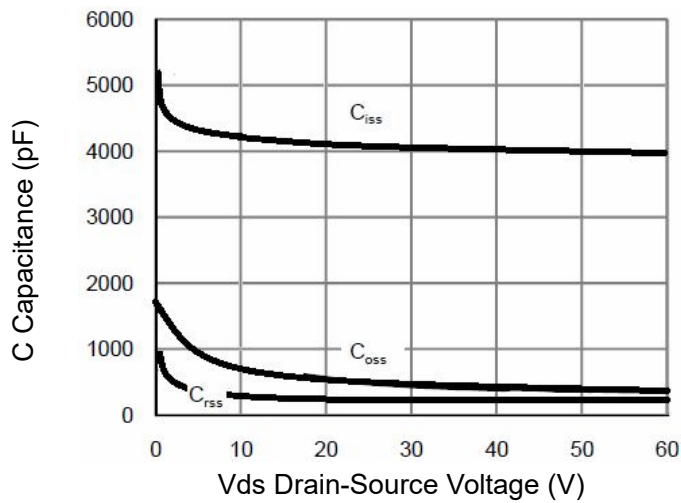
**Figure 4 Rdson-Junction Temperature**



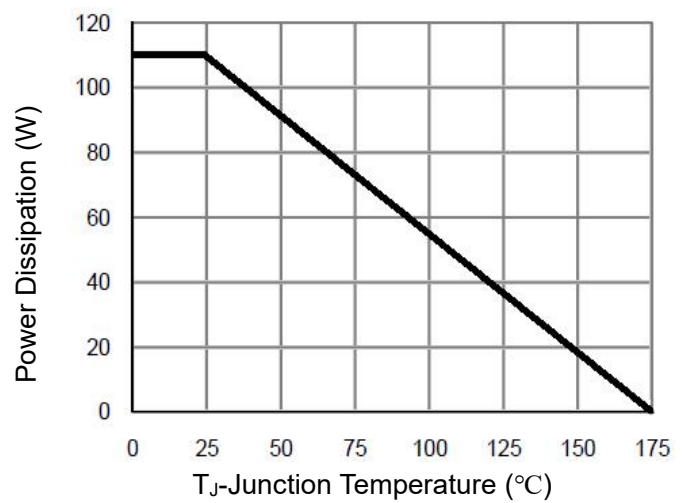
**Figure 5 Gate Charge**



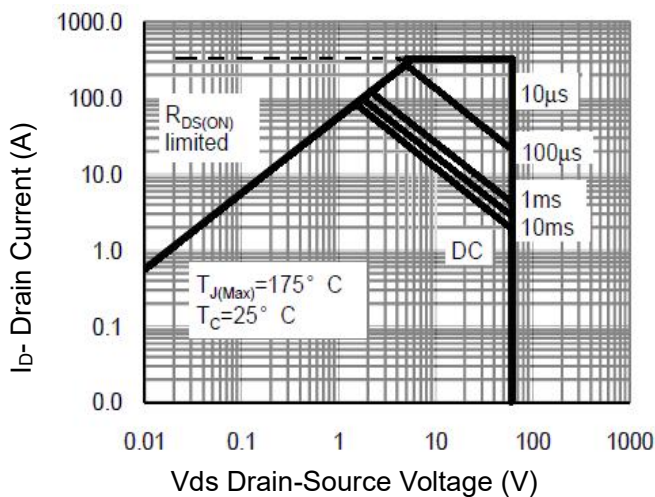
**Figure 6 Source- Drain Diode Forward**



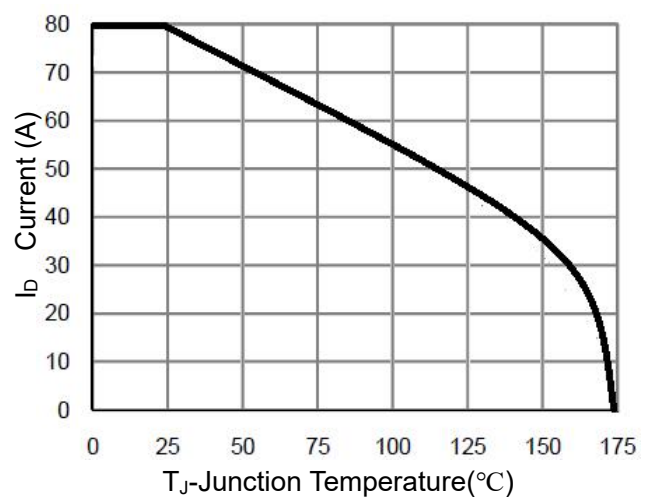
**Figure 7 Capacitance vs Vds**



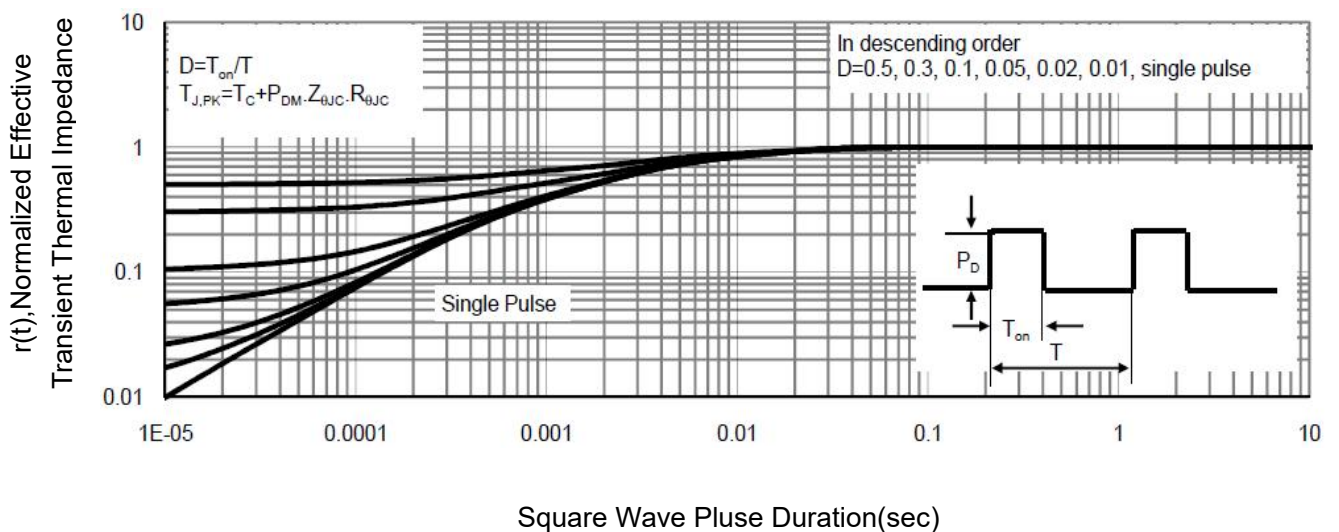
**Figure 9 Power De-rating**



**Figure 8 Safe Operation Area**

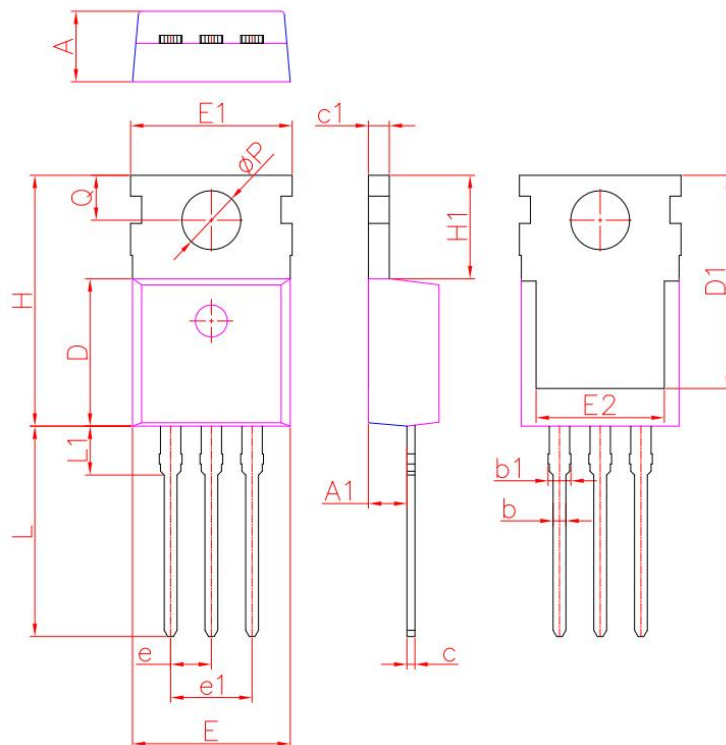


**Figure 10 ID Current- Junction Temperature**



**Figure 11 Normalized Maximum Transient Thermal Impedance**

## TO-220-3L Package Information



| TO220                         |         |       |       |
|-------------------------------|---------|-------|-------|
| DIM.                          | MIN.    | NOM.  | MAX.  |
| A                             | 4.20    | 4.40  | 4.60  |
| A1                            | 2.25    | 2.40  | 2.55  |
| b                             | 0.70    | 0.80  | 0.90  |
| b1                            | 1.17    | 1.27  | 1.37  |
| c                             | 0.33    | 0.50  | 0.65  |
| c1                            | 1.20    | 1.30  | 1.40  |
| D                             | 8.95    | 9.20  | 9.75  |
| D1                            | 13.10   | 13.30 | 13.50 |
| E                             | 9.74    | 9.84  | 10.04 |
| E1                            | 9.91    | 10.08 | 10.25 |
| E2                            | 7.90    | 8.00  | 8.10  |
| e                             | 2.54BSC |       |       |
| e1                            | 5.08BSC |       |       |
| H                             | 15.45   | 15.65 | 15.85 |
| H1                            | 6.30    | 6.45  | 6.60  |
| L                             | 12.90   | 13.13 | 13.40 |
| L1                            | 2.85    | 3.05  | 3.25  |
| Q                             | 2.65    | 2.80  | 2.95  |
| ØP                            | 3.40    | 3.68  | 3.80  |
| All dimensions in millimeters |         |       |       |

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